

Electronic Patent Application Fee Transmittal

Application Number:	10772651			
Filing Date:	04-Feb-2004			
Title of Invention:	Multi-chip package with soft element and method of manufacturing the same			
First Named Inventor/Applicant Name:	Dong-Kil Shin			
Filer:	Hosoon Lee/Stormi Davis			
Attorney Docket Number:	9898-341			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Claims in excess of 20	1202	1	50	50
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				50